



PRESS RELEASE:

Orbotech's SPTS Technologies Accelerates Industry Adoption of its Mosaic™ Plasma Dicing Solution with Order from JCAP Corporation

Industry Adoption of SPTS's Plasma Dicing Solution Further Verified by System Plus Consulting 'Teardown' Analysis of MEMS Microphones in iPhone 7 Plus

YAVNE, ISRAEL, March 8, 2017 | [ORBOTECH LTD.](http://www.orbotech.com) (NASDAQ: ORBK) today announced that SPTS Technologies, an Orbotech company and a supplier of advanced wafer processing solutions for the global semiconductor and related industries, has won an order for its Mosaic™ Plasma Dicing System from JCAP Corporation (Jiangyin Changdian Advanced Packaging Co., Ltd), a JCET company and leading Chinese advanced packaging services provider to global semiconductor companies. Orbotech's SPTS also announced that a recent analysis of MEMS microphones in the iPhone 7 Plus conducted by System Plus Consulting¹ confirmed that an ASIC device in the iPhone 7 Plus had been plasma diced.

Commenting on this recent order, Kevin Crofton, Corporate Vice President at Orbotech and President of SPTS Technologies, said: "JCAP selected Orbotech's SPTS plasma dicing solution over competing options because the Mosaic system demonstrated superior results and offers lower cost of ownership. We were also selected for our inclusive approach and willingness to work alongside other suppliers in the back-end space to produce sustainable process flows."

Mr. Crofton continued, "The Mosaic platform configured with the Rapier-300S is designed for handling 400mm framed wafers in a high volume manufacturing environment. It allows customers to offer industry-leading plasma dicing services that will meet the packaging needs of next generation devices. By adding plasma dicing to their service portfolio, customers can provide higher value packaging services and gain improved profitability in a highly cost sensitive industry."

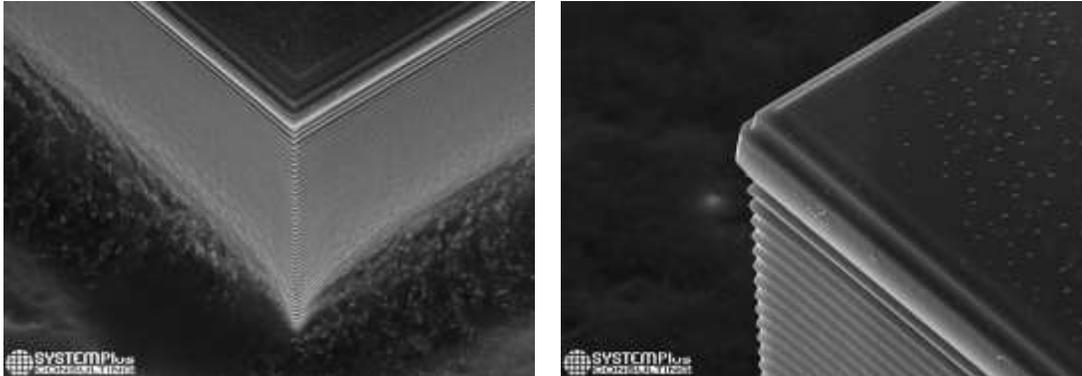
According to Amandine Pizzagalli, Technology & Market Analyst, at Yole Développement and author of the report entitled "Thin Wafer Processing and Dicing Equipment Market"², "Plasma dicing could reshape the dicing industry landscape by increasing the number of chips per wafer and thus reducing the cost of ownership of the dicing process. Driven by the rising demand for thinner wafers and stronger die,

¹ Knowles MEMS Microphones in iPhone 7 Reverse Costing Analysis, System Plus Consulting, October 2016

²Thin Wafer Processing and Dicing Equipment Market report, Yole Développement, May 2016

plasma dicing is positioned to become the only viable dicing option for next generation ultra small, ultra thin and fragile devices such as RFID, MEMS, and Power devices.”

Mr. Crofton added, “We have had continuous interest in the Mosaic plasma dicing solutions in our demo lab, and we continue to win business and expand our installed base. We see this as a real validation of our dicing platform. System Plus Consulting’s discovery of a plasma diced ASIC in the iPhone 7 Plus, which has been processed by our equipment, confirms industry acceptance and adoption of plasma dicing as a singulation method in the industry in high volume manufacturing.”



Images of plasma-diced ASIC in iPhone 7 Plus (Courtesy of System Plus Consulting)

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About Mosaic™ Plasma Dicing System

Orbotech's SPTS Mosaic™ plasma dicing system with the Rapier-300S overcomes many of the design limitations of conventional dicing methods, particularly for smaller, thinner, more fragile die, as well as offering the potential for significant increases in yield and throughput. The Rapier-300S is a silicon DRIE module, designed specifically for dicing of 300mm wafers mounted on 400mm frames and is available along with plasma dicing solutions for 150mm, 200mm and 300mm wafers. Unique aspects of SPTS's plasma dicing technology include the use of SPTS's patented Sentinel™ end-point detection and “bias pulsing” techniques to maximize die strength.

To learn more about SPTS's [Rapier-300S and Mosaic plasma dicing platform](#) go to the Tech Insights section for articles on [dice before grind \(DBG\)](#) and [dice after grind \(DAG\)](#). Published papers and presentations can also be found in the [Resources](#) section.

About Orbotech Ltd.

Orbotech Ltd. (NASDAQ:ORBK) is a global innovator of enabling technologies used in the manufacture of the world's most sophisticated consumer and industrial products throughout the electronics and adjacent industries. Orbotech is a leading provider of yield enhancement and production solutions for electronics reading, writing and connecting, used by manufacturers of printed circuit boards, flat panel displays,

advanced packaging, micro-electro-mechanical systems (MEMS), RF devices, power semiconductors, and other electronic components. Orbotech's solutions include automated optical inspection and shaping, direct imaging, laser drilling, Inkjet printing, array test and repair, yield management, and etch and deposition wafer process solutions.

Today, virtually every electronic device in the world is produced using Orbotech systems. For more information, visit www.orbotech.com and www.spts.com

Cautionary Statement Regarding Forward-Looking Statements

Except for historical information, the matters discussed in this press release are forward-looking statements within the meaning of the U.S. Private Securities Litigation Reform Act of 1995. These statements relate to, among other things, future prospects, developments and business strategies and involve certain risks and uncertainties. The words "anticipate," "believe," "could," "will," "plan," "expect" and "would" and similar terms and phrases, including references to assumptions, have been used in this press release to identify forward-looking statements. These forward-looking statements are made based on management's expectations and beliefs concerning future events affecting Orbotech and are subject to uncertainties and factors relating to Orbotech's operations and business environment, all of which are difficult to predict and many of which are beyond the Company's control. Many factors could cause the actual results to differ materially from those projected including, without limitation, cyclicalities in the industries in which the Company operates, the Company's production capacity, timing and occurrence of product acceptance (the Company defines 'bookings' and 'backlog' as purchase arrangements with customers that are based on mutually agreed terms, which, in some cases for bookings and backlog, may still be subject to completion of written documentation and may be changed or cancelled by the customer, often without penalty), fluctuations in product mix, within and among divisions, worldwide economic conditions generally, especially in the industries in which the Company operates, the timing and strength of product and service offerings by the Company and its competitors, changes in business or pricing strategies, changes in the prevailing political and regulatory framework in which the relevant parties operate, including as a result of the Brexit process and administration change in the United States, or in economic or technological trends or conditions, including currency fluctuations, inflation and consumer confidence, on a global, regional or national basis, the level of consumer demand for sophisticated devices such as smartphones, tablets and other electronic devices as well as automobiles, the Company's global operations and its ability to comply with varying legal, regulatory, exchange, tax and customs regimes, the timing and outcome of tax audits, including the ongoing audit in Israel (the amount of taxable income is subject to ongoing audit by the Israel tax authority and such audits often result in proposed assessments and any estimation of the potential outcome of an uncertain tax issue is a matter for judgment, which can be subjective and highly complex; however, the Company believes that it has provided adequately for any reasonably foreseeable outcomes related to the tax audit, but future results may include favorable or unfavorable material adjustments to estimated tax liabilities in the periods when the assessments are made or resolved or the audit is closed), the Company's ability to achieve strategic initiatives, including related to its acquisition strategy, the Company's debt and corporate financing activities; the final timing and outcome, and the impact, of the criminal matter and ongoing investigation in Korea, including any impact on existing or future business opportunities in Korea and elsewhere, any civil actions related to the Korean matter brought by third parties, including the Company's customers, which may result in monetary judgments or settlements, expenses associated with the Korean matter, ongoing or increased hostilities in Israel and the surrounding areas, and other risks detailed in the Company's SEC reports, including the Company's Annual Report on Form 20-F for the year ended December 31, 2016, and subsequent SEC filings. The Company assumes no obligation to update the information in this press release to reflect new information, future events or otherwise, except as required by law.

ORBOTECH COMPANY CONTACTS:

Rami Rozen
Director of Investor Relations
Tel: +972-8-942-3582
Investor.relations@orbotech.com

Tally Kaplan Porat
Director of Corporate Marketing
Tel: +972-8-942-3603
Tally-Ka@orbotech.com